Chapter 6 TRANSISTOR-TRANSISTOR LOGIC

The evolution from DTL to TTL can be seen by observing the placement of p-n junctions. For example, the diode D2 from Figure 2 in the chapter on DTL can be replaced by a transistor whose collector is pulled up to the power supply; transistor Q_2 in Figure 1 below. The p-n junction of D2 is replaced by the BE junction of Q2 and with the current gain of the transistor, the current going into the base of Q3 is greatly increased, increasing the fanout.







Figure 2. Configuration of Q_1 as a 3-emitter transistor.

The input diodes and D1 are replaced by the multi-emitter NPN transistor, Q1, in Fig. 1 and represented by the drawing in Figure 2. Later on, we will make additional modifications to this curcuit to improve its performance further.

The analysis of this circuit follows very much the same path as the analysis of the DTL gate. For the most part, we will consider the input transistor, Q1, to act just like two diodes. The transistor Q2, however, will operate in all three regions. The treatment of the output voltages and currents will be treated the same as the DTL gate and Q3 will either be cutoff or saturated, corresponding to an output high and an output low, respectively.

ANALYSIS WITH ONE OR MORE INPUTS LOW

With an input low, Q3 should be cutoff. We will assume Q2 is cutoff and then check our assumption. If Q2 is cutoff, then there can be no current coming out of the collector of Q1, hence its base-collector junction can be modeled as an open circuit. The base-emitter junction of Q1 will be conducting. The circuit with these models substituted for the transistors is shown in Figure 3. Note the similarity to the DTL circuit under the same conditions. The two unused inputs are assumed to be high, and are thus, modeled as open. From this case, we can see that $V_{oH} = 5$ volts with no load, and

$$I_{inL} = -I_1 = -(5-0.9)/4K = -1.025 \text{ mA}$$



Figure 3. TTL circuit model with one input low.

We turn now to finding V_{InLmax} . We will use the criterion that V_{in} will be considered as a low as long as Q3 is kept cutoff. If the base voltage for Q3 can be raised to 0.5 Volts without turning it on, then there will be 0.5 mA current in the 1K Ω resistor. This current can only come from Q2, which means it must be conducting. Even assuming all this 0.5 mA comes through the collector of Q2, the voltage drop across the 1.4 K Ω resistor will be 0.7 Volts, not enough to cause the transistor to saturate. Thus, the active model for Q2 is appropriate as shown in Figure 4.



Figure 4. TTL circuit model to determine V_{inLmax} .

If we assume that β =30, the base current in Q2 is

$$I_{B2} = \frac{0.5mA}{\beta + 1} = \frac{0.5}{31} = 0.016mA$$

Because this current is coming out of the collector of Q1, the base- collector junction of Q1 is on, and is modeled as a diode in Figure 4.

The voltage at B1, the base of Q1, is

$$V_{B1} = 0.5 + 0.7 + 0.7 = 1.9$$
 Volts

The current coming down through the 4 K Ω resistor, I₁, is

$$I_1 = \frac{5.0 - 1.9}{4K} = 0.775 mA$$

This is considerably more than is going into the base of Q2, therefore, the input BE junction of Q1 will also still be conducting. The maximum voltage at the input is

$$V_{inLmax} = 1.9 - 0.7 = 1.2$$
 Volts

Transistor-Transistor Logic

CALCULATIONS WITH INPUT HIGH

The circuit model for the TTL gate with all inputs high is shown in Figure 5. Both Q2 and Q3 are modeled as saturated, an assumption that must be verified. With the inputs high, Q1 is modeled as two diodes with the B-E diodes cutoff, and B-C diode conducting.



Figure 5. TTL gate circuit model with all inputs high.

The voltage at the base of Q1 is

 $V_{B1} = 0.8 + 0.8 + 0.7 = 2.3$ Volts.

The current down through the 4 K Ω resistor, I₁ is

$$I_1 = \frac{5.0 - 2.3}{4K} = 0.675 mA$$

All this current goes into the base of Q2.

$$I_{B2} = 0.675 \text{ mA}$$

If Q2 is saturated, voltage at its collector terminal is

$$V_{C2} = 0.8 + 0.2 = 1.0$$
 Volts

And the collector current is

$$I_{C2} = I_2 = \frac{5.0 - 1.0}{1.4K} = 2.857mA$$

Clearly, if $\beta = 30$, $\beta I_{B2} > I_{C2}$, and, therefore, Q2 is saturated.

The current coming out of the emitter of Q2 is the sum of the base and collector currents. Part of this current will go down through the 1 K Ω resistor to ground and the rest will enter the base of Q3.

$$I_{B3} = I_{B2} + I_{C2} - I_3 = 0.675 + 2.857 - 0.8 = 2.732 \text{ mA}$$

The maximum collector current that Q_3 can carry and still be in saturation is $\beta I_{B3} = 81.96$ mA, assuming $\beta = 30$. The maximum current the gate can sink when the output is low

 $I_{oLmax} = I_{Csatmax} - I_4 = 81.96 - 1.2 = 80.76 \text{ mA}$

Now let's turn our attention back to the input and determine V_{inHmin} and I_{inH} . We will define the input voltage to be high as long as no current goes out the input terminal. Thus, all we have to do is keep the input voltage high enough so that the B-E p-n junction of Q1 does not turn on. Thus,

 $V_{inHmin} = 2.3 - 0.6 = 1.7$ Volts

CALCULATION OF I_{inH}

With the input voltage at a high, say 5 volts, the transistor Q1 will be operating in the reverse active mode. The B-E junction is reverse biased, and the B-C junction is forward biased with a base current of 0.675 mA. If there were significant curent gain, you would expect to see a large current going into the input. However, the reverse β is typically on the order of 0.02. Thus,

 $I_{inH} = \beta_R * I = 0.02 * 0.675 = 0.0135 \text{ mA}$

This current would add to the current going into the base of Q2, but is ignored because it is quite small and because β_R is made as small as possible and this input current is a maximum and cannot be counted on.

THE TOTEM POLE OUTPUT STAGE

One of the problems with the TTL gate circuit we have been analyzing is that the pull-up resistor on the output transistor will prevent rapid charging of any wiring capacitance on the output. One way to improve the rise time is to reduce the resistance value as is often done, but this also increases the power dissipation when the output is low.

If we look at the circuit, we observe that when the transistor is saturated, it presents a very low effective resistance to ground. The problem arises when the output is high and the pull-up resistor is too large. Ideally we would like to have a very low resistance pull-up when the output is high, but a very high pull-up resistance when the output is low. In this way, we could get quick charging and very low power dissipation. The totem-pole output stage for TTL, shown in Figure 6, does just that.



Figure 6. TTL gate with totem-pole output.

This circuit operates just like the original circuit except that Q_4 is on when the output is high and off when the output is low. We need to verify this operation.

OUTPUT LOW

Figure 7 shows the TTL circuit with all inputs high and the output low. The models for the transistors are shown as before, except diode D and transistor Q_4 are added and shown as cutoff.



Figure 7. TTL gate with totem-pole output circuit model with inputs high.

The analysis of this circuit proceeds exactly the same as before. The currents, I_1 , I_2 , I_3 , and I_{B3} are the same as before. With the diode and Q_4 not conducting, I_{oLmax} is now the same as I_{C4max} , 81.96 mA. We only need to show that the diode D and transistor Q_4 are indeed off.

The voltage at the bottom of the diode is 0.2 Volts and the voltage at the base of Q_4 equal to the voltage at the collector of Q_2 ; $V_{C2} = (0.2 + 0.8) = 1.0$ Volts. Thus, the voltage across the B-E junction of Q_4 plus the diode is 0.8 Volts. If one conducts, the other must also. To take both out of cutoff would require at least 0.5 + 0.6 = 1.1 Volts. Thus, both are off.

OUTPUT HIGH

This condition occurs when one or more inputs are low. The circuit is shown in Figure 8 with the appropriate models used for the transistors and the diode. In this case, Q2 and Q3 are both cutoff while Q4 and the diode are conducting. We have to assume here that there is some load and that the output current is not zero.



Figure 8. TTL totem-pole circuit model with output high.

The current coming out the output terminal I_S (=- I_o) is the sum of the currents coming down through the base and the collector. Thus,

$$I_S = I_{B4} + \beta I_{B4}$$

Because each TTL load represents 13 μ A, if we assume there are 10 loads, then I_S = 130 μ A. The base current is

$$I_{B4} = \frac{130\mu A}{1+\beta} = 4.2\,\mu A$$

where we have assumed a β of 30. Then taking the path down through the 1.4 K Ω resistor to the output. the output voltage is

$$V_0 = 5.0 - 4.2 \mu A * 1.4 K - 0.7 - 0.7 = 3.6 Volts$$

The voltage drop across the 1.4 K Ω resistor is neglegible. Of course as the current increases, the output voltage will drop further.

TERMINAL SPECIFICATIONS OF THE TTL GATE

We are now ready to make the table showing the terminal specifications for the TTL gate. These are shown in Table 1.

$V_{inLmax} = 1.2 V$	$V_{oL} \ = 0.2$
$V_{inHmin} = 1.7$	$V_{oH} = 3.4 \ (@I_o = -130 \ \mu A)$
$I_{inL} = -1.025 \text{ mA}$	$I_{oLmax} = 81.96 \text{ mA}$
$I_{inH} = 13 \ \mu A$	I_{oH} = undetermined

Table 1. Terminal Specifications For TTL

TTL DATA

Recommended Operating Conditions

		74	74H	74L	74LS	74S	Units
Voca	and — Vocement	4.75-5.25	4.75-5.25	4.75-5.25	4.75-5.25	4.75-5.25	V
Іан		-400	-500	-200	-400	-1000	μA
Ial		16	20	3.6	8	20	mΑ
Operating Free-Air Temperature Range		0 - 70	0 - 70	0 - 70	0 - 70	0 - 70	°C
Electrical Characteristics Over Recommended Operating Temperature Range Ondition 74 74H 74L 74LS 74S U							Units
ViHebe	1	2.00	2.00	2.00	2.00	2.00	V
VILIMAN		0.80	0.80	0.70	0.80	0.80	V
V _{O Hebe}	@ I _{он} = max	2.40	2.40	2.40	2.70	2.70	v
Valeer	@ I _{or} = max	0.40	0.40	0.40	0.5	0.5	v
Іінжах	- 	40	50	10	20	50	μA
ILLERAN		-1.60	-2.00	-0.18	-0.40	-2.00	mA
ľaz	 * 	-2055	-40100	-315	-20100	-40100	mA

* Not more than one output should be shorted at a time and for H, LS, and S series, duration of short should not exceed one second.

Figure 9. Data for '00, '04, '10, and '30 NAND gates for several TTL families (Abstracted from Texas Instruments TTL Data Book.)

MANUFACTURER'S DATA SHEETS

The terminal specifications of several TTL families are shown in Figure 9. You will note the values given for various voltages and currents are quite different from those we calculated. This difference comes from the fact that manufacturing tolerances and variations cannot be closely controlled, hence, the specifications given by the manufacturers are much more conservative than our calculations which were based on nominal values. Also note that the limits are usually given as a maximum or a minimum, depending on which limit is normally used in design. For example, I_{inLmax} is given as -1.6 mA for the 74xx series. What this means is that as a designer, your driver must be able to sink as much as 1.6 mA when the input to the gate is pulled low.

You will note that the TTL gate is rather loosely specified. The question invariably arises as to how one reads the data sheets or designs with this data. Figure 10 shows the allowed operating regions for a 7400, 2-input NAND gate. The best description of these operating regions is probably given by the following examples.

- Example 1: If the input voltage is between 0.00 and 0.08 volts, the output voltage will be below V_{CC} and above 2.4 volts as shown in Figure 10a.
- Example 2: If the input voltage is between 2.00 and V_{CC} , the input current will be between 0 and 40 μ A as shown in Figure 10b.

You will note in the above examples that there is no mathematical relationship between one variable and another. There is simply not enough data to develop one and the variability of the manufacturing process prohibits the manufacturer from providing one.

In a design setting, you must stay within the limits provided by the manufacturer. For example, if you wanted to connect a resistor from the output of a 7400 gate and ground, what would be the limits allowed on the resistance value? Figure 10c provides part of the answer. If we assume that we must operate within the shaded region which represents a "High" level output, we should not allow the output to drop below 2.4 volts with 400 μ A coming out of the gate. The minimum value would be 6 K Ω . The upper limit is, of course, infinite; an open circuit (V₀ = V_{CC}, I₀ = 0).

There are a few data points provide by the specifications that are not within the limits of normal operation. For example, if the input voltage drops below zero, it is allowed to drop to -1.5 volts where you may expect as much as 12 mA coming out of a 7400 gate input. Most of this current comes from an input clamp diode which has not been shown on our drawings.



a. Allowed operating region, $V_{\rm out}$ vs $V_{\rm in}$, for a 7400 gate.



c. Allowed operating region, I_{out} vs V_{out}

Figure 10. Allowed operating regions for a 7400 gate.

Another non-standard data point of interest is I_{oS}, the short-circuit output current. This is the current you get from the gate output if the output is shorted to ground when the output of the gate would otherwise be high. In this case, both minimum and maximum values are given, -18 to -55 mA. If you went to the laboratory and actually performed this deed, you could expect a current somewhere in this range. How does this affect the designer? For example, a designer might be tempted to connect the output of the 7400 gate directly to the base of an NPN transistor whose emitter is grounded. In this case, the "high" output voltage is clamped at 0.80 V by the BE junction. What current can you expect into the base of the transistor when the gate output goes "high"? This condition is tricky and perhaps open to some debate, but the conservative designer must recognize that the operation is between the short circuit case and the case where V_{oHmin} =2.4V when I_{oH} =-400µA. The conservative designer would conclude that the current might be as low as 400 μ A and as high as 55 mA; the worst cases. It is possible to go back to the circuit of the gate with 0.8 volts at the output terminal and calculate the current. However, this analysis would be for nominal values only and not provide definitive limits on the current.

Note the notation at the bottom of the specification table in Figure 9. This notation discusses the limit on the amount of time a short circuit is allowed to be connected to the output of some gates. This time limit is based on the amount of time it takes the internal components of the integrated circuit to heat up to its maximum allowed value. While connecting a transistor base to the output is not exactly a short circuit, it is outside the allowed operating region and probably should have the same time limits as the short circuit.

TERMINAL CHARACTERISTICS

During the previous discussions on TTL, we were looking at circuit operation and developing an understanding of how the terminal specifications were arrived at. Let us now take a broader look at these characteristics.

First, the input currents are quite high when the input is low, requiring the driver to **sink** a lot of current. When the input is high, the input current into the gate is quite low. Thus, any circuit which is supposed to drive the input to a TTL gate must concentrate on sinking current, and only needs to source a little current when the driver output voltage is high.

Second, the output strength of the TTL gate matches the strength requirements at the input. An example is given in Figure 11. The TTL gate can sink a large current when its output is low, but can only source a small current when the output is high. Thus, if the TTL gate is expected to drive a circuit that is not another TTL circuit, you must exercise care when designing the interface. The load circuit must not require large input currents when its input is high, but may use larger currents when the input voltage is low.



Figure 11. When driving other TTL gates as loads, a 7400 gate must be able to sink more current than it needs to source.

These requirements must be kept in mind when designing interfaces with the TTL gate at both the input and the output. Examples of interfacing with TTL gates are shown in Figure 12 and 13. See data books for more complete data.







Figure 13. Several interfaces to drive TTL gates.

WIRED-AND CONNECTION

Because the active pull-up or totem-pole output of the TTL gate always has one transistor cutoff and the other turned on, you cannot connect two outputs together. If one is trying to pull the output high, and the other is trying to pull it low, you will have a very low impedance path to ground and very large currents.

For the same reason, the output must not be connected to any voltage source or to ground through a low impedance path. In one state or the other, there would be a low impedance path and large currents.

OPEN COLLECTOR GATES

In order to overcome the limitations created by the totem pole output circuit, some gates are manufactured with the output collector left open. One example is the 7405, a quad 2-input NAND gate with open collector outputs. If you connect a resistor as the pull-up, you can use this resistor to source current when the output is high and/or you can wire-AND the collectors together.

TTL FAMILIES

As the designers of TTL gates became more sophisticated, they developed modifications which would provide special characteristics. The original series of TTL was designated as 74XX, where the XX is replaced by logic function (00 is a quadruple 2-input NAND, 04 is a hex inverter, etc.) The 74LXX series is a low power family. 74HXX is a high speed family. 74SXX is a family based on Schottky diodes and transistors. 74LSXX is a family of low power Schottky. A 54xXX is also provided as a companion family to the 74xXX families. The 54... families are identical to the 74... families, except for operating temperature range and tolerance on power supply voltage.

Each family has different characteristics, but the same logic functions. The L family is low power, but is much slower than the standard family. The H family is high speed, but also has higher power dissipation. The Schottky families are quite fast without increasing the power dissipation. More recent advances in TTL family have given us several other versions. For example, 74F, 74AS, and 74ALS, for Fast, Advanced Schottky, and Advanced Low-power Schottky. The AS family is the fastest, with a propagation delay of less than 5 ns. Table 2 shows the propagation delays and power supply current for each type of gate. The power supply current, I_{CC} , is the average for a 50% duty cycle with the output spending half its time low and half the time at a high.

In addition, these different families use slightly different circuit configurations. A little study of the circuits will reveal the same operations.

Gate	t _{PLH} (ns)			t _{PHL} (ns)			I _{CC} (mA)
	min	typ	max	min	typ	max	typical
7400		11	22		7	15	2.00
74L00		35	60		31	60	0.20
74H00		5.9	10		6.2	10	4.50
74LS00		9	20		10	20	0.40
74S00	2	3	4.5	2	3	5	3.75
74ALS00	3		11	2		8	1.00
74AS00	1		5	1		4	6.20

 Table 2. Propagation delays and power supply current for TTL families

 Data abstracted from Texas Instruments TTL Data Books

SCHOTTKY TTL

A Schottky PN junction is made up of a semiconductor and a metal. This kind of junction has two characteristics: low turn-on voltage and low junction capacitance.

When a Schottky junction is used in place of or in parallel to the Base-Collector junction of a transistor, the transistor is faster because of the lower junction capacitance and because the transistor cannot go so deep into saturation. Because the turn-on voltage for the BC junction is lower, V_{CEsat} is higher.

Schottky TTL is thus faster than standard TTL and the terminal voltages are slightly different. See the data sheet.

TRI-STATE OUTPUT

The totem-pole output of a TTL gate provides additional speed at lower power for the gate than a simple pull-up resistor. The cost, however, is that the gate outputs cannot be connected in parallel. This problem is serious when you need to make a bus structure such as a data bus, where several gates need to put data onto the bus at different times. The outputs can be OR'd or AND'ed using appropriate gates, but this solution is less than satisfactory and slows down the operation.

A better solution is the TRI-STATE output as shown in Figure 14. The added input allows normal operation of the gate when the "enable" input is high. Both output transistors are cutoff when "enable" is low.



Figure 14. TTL gate with Tri-State output.

OTHER LOGIC FUNCTIONS IN TTL

TTL integrated circuits have been manufactured that perform over one hundred different functions. Many are small-scale integrated circuits that perform simple logic functions in addition to the basic NAND as well as flip-flops. Others are medium-scale integrated circuits that perform more sophisticated functions such as encoders, decoders, and registers. The more complex functions are implemented in TTL using combinations of the basic logic gates. It is of interest to look at how some of the other logic functions are implemented. Figures 15, 16, and 17 show a NOR gate, an AOI gate (AND-OR-INVERT), and an AND gate.

In each case, the input and output circuits are the same as for the NAND gate. Extra parts are added to perform the desired function. For example, the NOR gate has extra Q_1 and Q_2 added in parallel to the existing transistors. The extra emitters in Q_1 are left out. These extra emitters perform the AND function in the NAND gate. The OR is performed by the Q_2 s in paarallel. The final inversion is performed by the output stage by Q_3 . Note the similarity to the AOI gate in which the AND function is intact with the extra emitters in the Q_1 s.

The AND gate in Figure 16 has an extra internal inversion. The actual inversion is done with Q_5 . The other additional transistor, Q_6 is used simply to guarantee Q_2 is turned off when Q_5 is turned on. This extra transistor is necessary to maintain voltage levels consistent with the NAND gate.



Figure 15. TTL NOR gate implementation



Figure 16. TTL AND-OR-INVERT (AOI) gate implementation



Figure 17. TTL AND gate implementation

How do these modifications in the basic TTL circuit affect propagation delays? Table 3 show the typical and maximum propagation delays for each type of gate discussed. It is apparent from the table that the addition of the extra internal inverter stage in the AND gate does have a significant effect on propagation delays while the addition of the parallel circuits for the NOR and AOI gates has very little effect. This latter effect is caused primarily by the addition of internal capacitance.

Logic Gate	t _{PLH}	(ns)	t _{PHL} (ns)		
	typ	max	typ	max	
7400 (NAND)	11	22	7	15	
7402 (NOR)	12	22	8	15	
7408 (AND)	17.5	27	12	19	
7451 (AOI)	13	22	8	15	

Table 3. Propagation delays for NAND, NOR, AND, and AOI gates. Data abstracted from Texas Instruments TTL Data Book

EXERCISES

1. For the TTL NAND gate circuit shown draw a wire connecting both inputs to +5 volts. Then:

- a. Indicate the output logic level:
- b. Indicate the state of each transistor and the diode.

 Q_1 _____, Q_2 _____, Q_3 _____, Q_4 _____, D _____

c. On the diagram, draw an arrow showing the direction of current in each branch.



2. On the circuit below, draw wires connecting one input to ground and the other to +5 volts. Then:

- a. Indicate the output logic level:
- b. Indicate the state of each transistor and the diode.



c. On the diagram, draw an arrow showing the direction of current in each branch.



3. For the TTL NOR gate circuit shown draw a wire connecting both inputs to ground. Then:

- a. Indicate the output logic level:
- b. Indicate the state of each transistor and the diode.
- Q_{1a} _____, Q_{1b} ____, Q_{2a} ____, Q_{2b} ____, Q_{3} ____, Q_{4} ____, D _____
- c. On the diagram, draw an arrow showing the direction of current in each branch.



4. For the TTL NOR gate circuit shown draw a wire connecting the A input to +5 volts and the B input to ground. Then:

- a. Indicate the output logic level:
- b. Indicate the state of each transistor and the diode.

 Q_{1a} _____, Q_{1b} _____, Q_{2a} _____, Q_{2b} _____, Q_{3} _____, Q_{4} _____, D _____

c. On the diagram, draw an arrow showing the direction of current in each branch.



5. Assume the following circuit is connected on a proto-board in the laboratory. You are troubleshooting the circuit. The gates are all 74LS00.

- a. What voltage do you expect at each node, A-E?
- b. What current would you expect in each branch, (beside each arrow)?

6. In most cases a resistor is used bewteen an input terminal and +5 volts to make a "1" at the input. Sometimes a resistor is used to pull-down the input to a zero. Both cases are shown below. What is the maximum value in each case?

a. R_{pull-up max} b. R_{pull-down max}

7. Calculate the minimum resistor allowed in each case for the two 74LS00 gates below.

a. R_{pull-up min} _____ b. R_{pull-down min} _____

Problems

1. You are in the midst of designing a combination portable computer/walkman/Internetcellphone which you intend to market and hopefully become a millionaire. To complete the design you need a 3-input NAND gate. The only store open at this time of night is the Handy-Combo Electronics/Oil Change/Hair Style/Pizza Parlor where you purchase the TTL gate shown below. Unfortunately, there are no specifications except that $\beta_{sat} = 15$ and $\beta_r = 0.05$. You must determine the specifications for this gate before you can use it. List the eight terminal current and voltage specifications in tabular form.

2. Make a compatibility chart for three TTL series shown in the data sheet in Figure 9 of the text. This chart is a matrix showing how many loads of a particular series can be driven by a driver of the same or another series, all of course, within specifications given by the manufacturer.

3. The two gates shown in the diagram labeled problem 3 are 74LS00. Gate A is used to drive gate B as well as the two-transistor buffer circuit. When the output of Gate A is high the load is turned off. When the output of gate A is low, the load is carrying current. Gate B should see valid logic levels and must operate properly. Determine the absolute maximum current that can be delivered through the load using the following characteristics for the buffer transistors.

 $V_{BEcutin} = 0.5$ volts, $V_{BEsat} = 0.8$ volts, $V_{CEsat} = 0.2$ volts, $Beta_{sat} = 20$

Problem 3

Problem 4

4. In the above logic system for problem 4, the output connection for each of the eight gates is numbered. If you were to measure the current in each of these wires, what is the maximum value you would expect to find? Use the specifications in Figure 9. For the load resistors connected to outputs 6 and 7, give the allowable range assuming valid logic output voltage levels. The symbols inside the gate indicate the family. No symbol indicates a 7400 gate.

5. Draw the figures showing the allowed operating regions, as shown in Figure 9 in the textbook for a 74S00 gate.

6. Laboratory Measurement

For a 7400 gate, make the following measurments:

a. No-load output voltage b. V_{inLmax} c. V_{inHmin}

For the last two measurement, describe the criteria you used to determine the limits.

7. A TTL gate has the following specifications:

 $V_{inLmax} = 1.00$ $V_{inHmin} = 2.00$ $I_{inL} = -0.500$ $I_{inH} = 1.00$

 $V_{oLmax} = 0.50 V_{oHmin} = 2.50 I_{oLmax} = 5.50 I_{oHmax} = -7.00$

In both cases below, the gate must see a Low with the switch in one position and a High with the switch in the other position.

a. Determine the allowed values of resistor R_D in the circuit below.

b. Determine the allowed values of resistor R_E in the circuit below.

